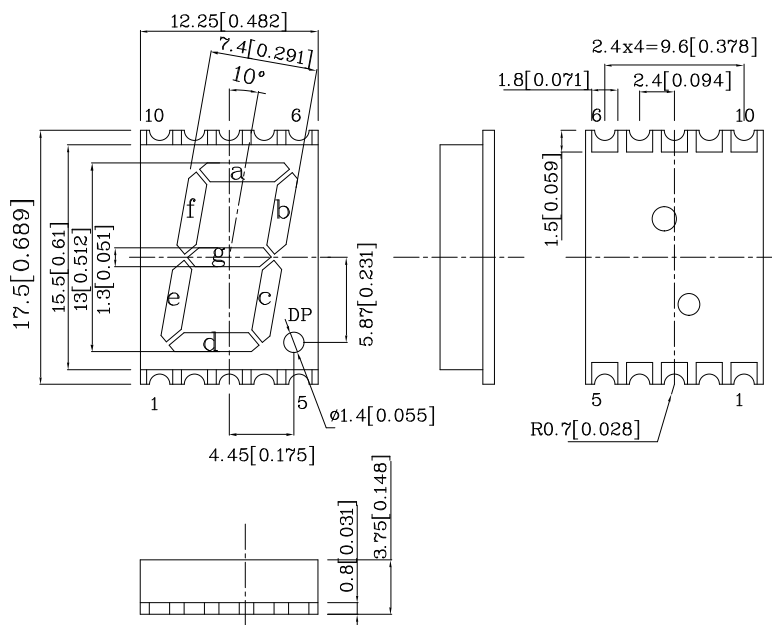
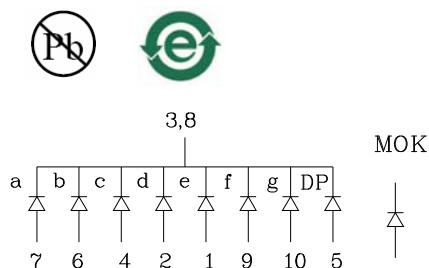


PRELIMINARY SPEC

Features

- 0.51 INCH DIGIT HEIGHT.
- LOW CURRENT OPERATION.
- I.C. COMPATIBLE.
- MECHANICALLY RUGGED.
- GRAY FACE, WHITE SEGMENT.
- PACKAGE: 400PCS / REEL.
- MOISTURE SENSITIVITY LEVEL : LEVEL 4.
- RoHS COMPLIANT.



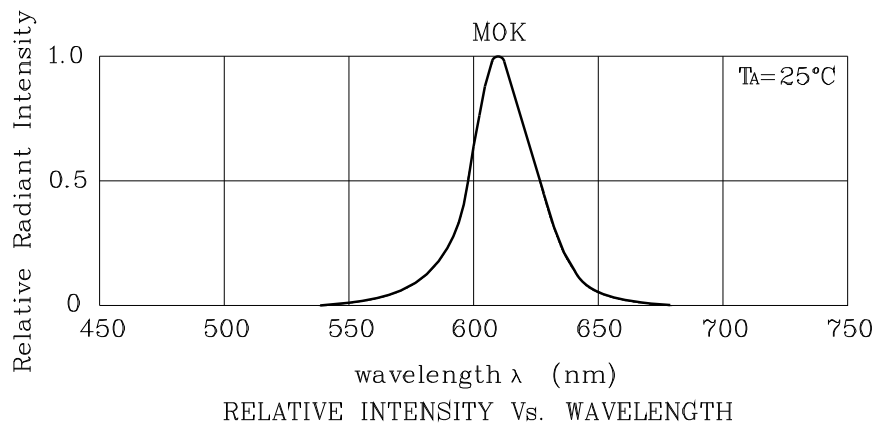
Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.
3. The gap between the reflector and PCB shall not exceed 0.25mm.
- 4.Specifications are subject to change without notice.

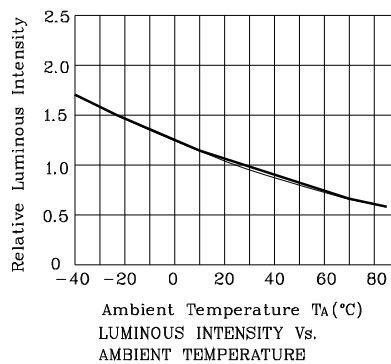
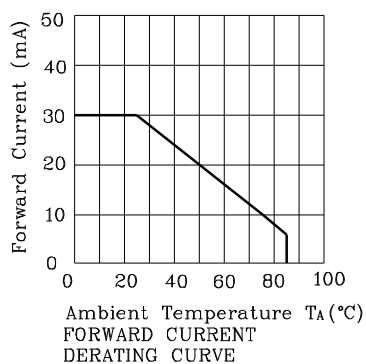
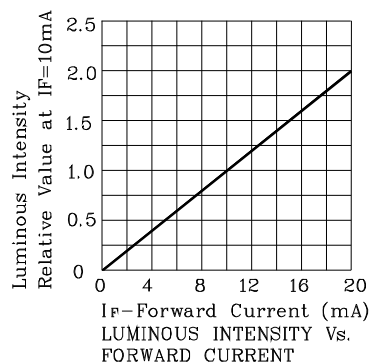
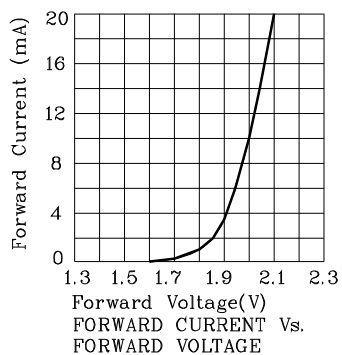
Absolute Maximum Ratings (TA=25°C)		MOK (InGaAlP)	Unit
Reverse Voltage	V _R	5	V
Forward Current	I _F	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i _{FS}	195	mA
Power Dissipation	P _T	75	mW
Operating Temperature	T _A	-40 ~ +85	°C
Storage Temperature	T _{stg}	-40 ~ +85	

Operating Characteristics (TA=25°C)		MOK (InGaAlP)	Unit
Forward Voltage (Typ.) (I _F =10mA)	V _F	2.0	V
Forward Voltage (Max.) (I _F =10mA)	V _F	2.5	V
Reverse Current (Max.) (V _R =5V)	I _R	10	uA
Wavelength Of Peak Emission (Typ.) (I _F =10mA)	λ _P	610	nm
Wavelength Of Dominant Emission (Typ.) (I _F =10mA)	λ _D	601	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =10mA)	Δλ	29	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	C	15	pF

Part Number	Emitting Color	Emitting Material	Luminous Intensity (IF=10mA) ucd		Wavelength nm λ P	Description
			min.	typ.		
ZFMOK129C	Orange	InGaAlP	12000	57990	610	Common Cathode, Rt. Hand Decimal
Published Date : FEB 27, 2008		Drawing No : SDSA6460		V1	Checked : Shin Chi	P.1/4



❖ MOK



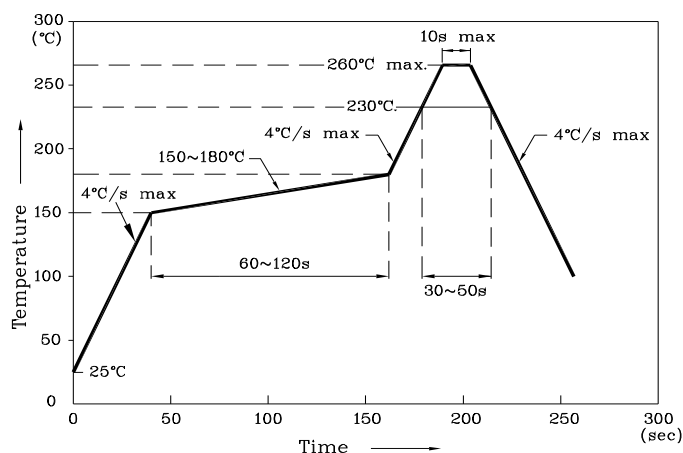
Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: $\pm 1\text{nm}$
2. Luminous intensity / luminous flux: $\pm 15\%$
3. Forward Voltage: $\pm 0.1\text{V}$

Note: Accuracy may depend on the sorting parameters.

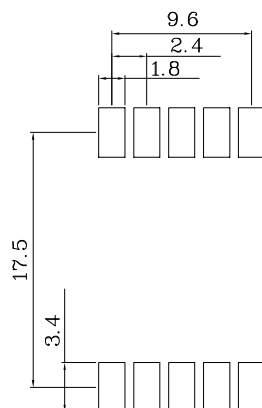
Reflow Soldering Profile For Lead-free SMT Process.



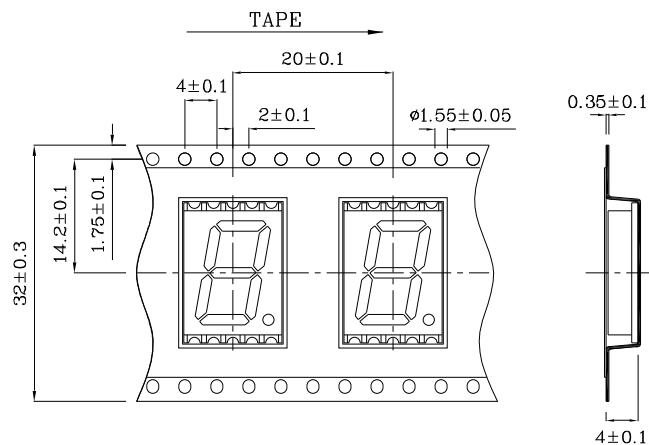
Notes:

1. Maximum soldering temperature should not exceed 260°C.
2. Recommended reflow temperature: 145°C-260°C.
3. Do not put stress to the epoxy resin during high temperatures conditions.

❖ Recommended Soldering Pattern (Units : mm;Tolerance:± 0.15)

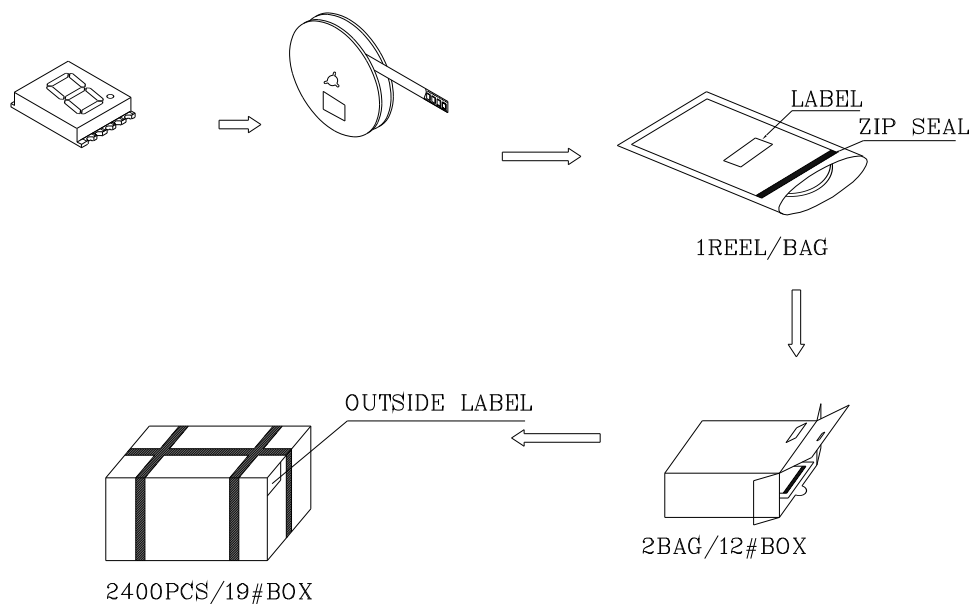


❖ Tape Specification (Units : mm)



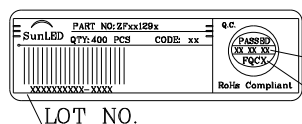
PACKING & LABEL SPECIFICATIONS

ZFMOK129C

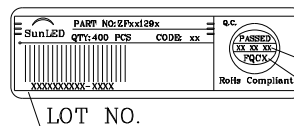


Outside LABEL Paste On The BAG

Inside LABEL Paste On The TAPE



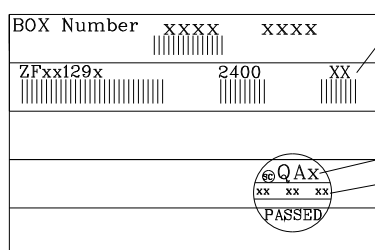
Date
Number OF FQC



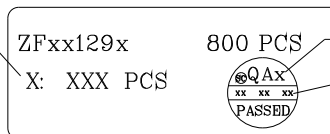
Date
Number OF FQC

Outside LABEL Paste On The 19#Box

Outside LABEL Paste On The 12#Box



BIN CODE
Date
Number OF QA



Number OF QA
Date